

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chun-Tsung Kuo	08/11/2010
Shih-Chang Liu	08/11/2010
Chia-Shiung Tsai	08/11/2010
<b>RECEIVING PARTY DATA</b>	
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<b>Street Address:</b>	No. 8, Li-Hsin Road 6
<b>City:</b>	Hsin-Chu
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12874362
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<b>ATTORNEY DOCKET NUMBER:</b>	24061.1478
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**PATENT**  
**REEL: 024929 FRAME: 0911**

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Docket No.: 2010-0200 / 24061.1478  
Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- |     |                  |    |                                                                                              |
|-----|------------------|----|----------------------------------------------------------------------------------------------|
| (1) | Chun-Tsung Kuo   | of | No. 28, Ln. 200, Yude 2 <sup>nd</sup> Rd., North District<br>Tainan City 704, Taiwan, R.O.C. |
| (2) | Shih-Chang Liu   | of | No. 21-1, Yuku Village, Alian Township<br>Kaohsiung County 822, Taiwan R.O.C.                |
| (3) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road<br>Hsin-Chu, Taiwan, R.O.C.                         |

have invented certain improvements in

### SPACER STRUCTURE FOR TRANSISTOR DEVICE AND METHOD OF MANUFACTURING SAME

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
\_\_\_\_\_ filed on 09-02-2010 and assigned application number 12/874,362; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu County 310, Taiwan, R.O.C., Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chun-Tsung Kuo

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Dated: 2010, 8, 11

*Chun-Tsung Kuo*  
*[Signature]*  
Inventor Signature

Inventor Name: Shih-Chang Liu

Residence Address: No. 21-1, Yuku Village, Alian Township  
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Dated: 2010.08.11

*Shih-chang Liu*  
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Inventor Signature

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Dated: 2010, 08, 11

*Chia Shiung Tsai*  
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